PCA9701; PCA9702

18 V tolerant SPI 16-bit/8-bit GPI with $\overline{INT}$

Rev. 02 — 29 August 2007 Product data sheet

1. General description

The PCA9701/PCA9702 are low power 18 V tolerant SPI General Purpose Input (GPI) shift register designed to monitor the status of switch inputs. It generates an interrupt when one or more of the switch inputs change state. The input level is recognized as a HIGH when it is greater than $0.7 \times V_{DD}$ and as a LOW when it is less than $0.4 \times V_{DD}$. The PCA9701 can monitor up to 16 switch inputs and the PCA9702 can monitor up to 8 switch inputs.

The falling edge of the $\overline{CS}$ pin samples the input port status and clears the interrupt. When $\overline{CS}$ is LOW, the rising edge of the SCLK loads the shift register and shifts the value out of the shift register. The serial input is sampled on the falling edge of SCLK.

Each of the input ports has a 18 V breakdown ESD protection circuit. When used with a series resistor (minimum 100 kΩ), the input can connect to a 12 V battery and support double battery, reverse battery, and load dump conditions in automotive applications. Higher voltages can be tolerated on the inputs depending on the series resistor used to limit the input current.

With both the high breakdown voltage and high ESD, these devices are useful for both automotive and mobile applications.

2. Features

- 16 general purpose input ports (PCA9701) or 8 general purpose input ports (PCA9702)
- 18 V tolerant input ports with 100 kΩ external series resistor
- Open-drain interrupt output
- Interrupt enable pin (INT_EN) disables interrupt output
- V_{DD} range: 2.5 V to 5.5 V
- I_{DD} is very low 2.5 µA maximum
- SPI serial interface with speeds up to 5 MHz
- AEC-Q100 qualification available
- ESD protection exceeds 8 kV HBM per JESD22-A114 (INT_EN is 7.5 kV), 600 V MM per JESD22-A115, and 1000 V CDM per JESD22-C101
- Latch-up testing is done to JEDEC Standard JESD78 which exceeds 100 mA
- Operating temperature range: –40 °C to +125 °C
- PCA9701 offered in SO24, TSSOP24 and HWQFN24 packages
- PCA9702 offered in TSSOP16 package

3. Applications

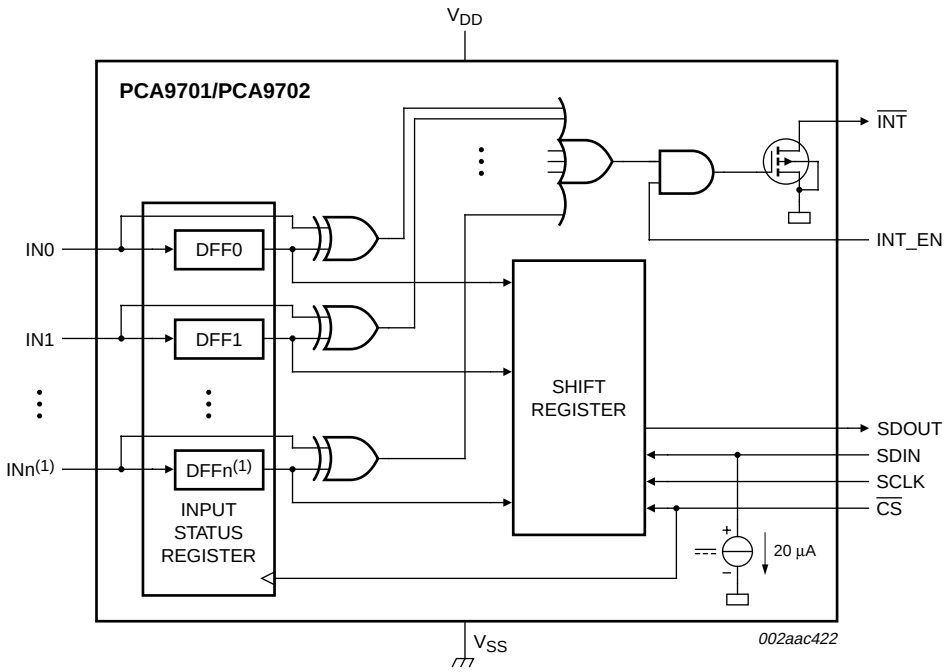
- Switch monitoring
- Industrial equipment
- Cellular telephones
- Emergency lighting

4. Ordering information

Table 1. Ordering information

Type number	Topside mark	Package		
		Name	Description	Version
PCA9701HF	9701	HWQFN24	plastic thermal enhanced very very thin quad flat package; no leads; 24 terminals; body 4 × 4 × 0.75 mm	SOT994-1
PCA9701D	PCA9701D	SO24	plastic small outline package; 24 leads; body width 7.5 mm	SOT137-1
PCA9701PW	PCA9701PW	TSSOP24	plastic thin shrink small outline package; 24 leads; body width 4.4 mm	SOT355-1
PCA9702PW	PCA9702	TSSOP16	plastic thin shrink small outline package; 16 leads; body width 4.4 mm	SOT403-1

5. Block diagram



(1) n = 15 for PCA9701; n = 7 for PCA9702

Fig 1. Block diagram of PCA9701; PCA9702

6. Pinning information

6.1 Pinning

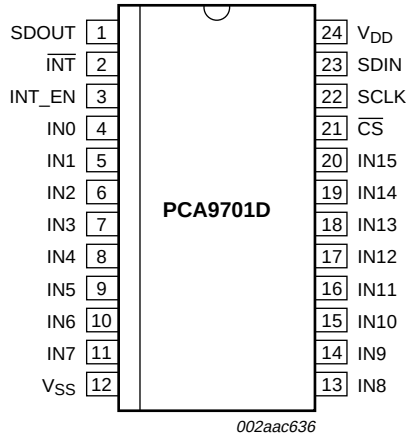


Fig 2. Pin configuration for SO24

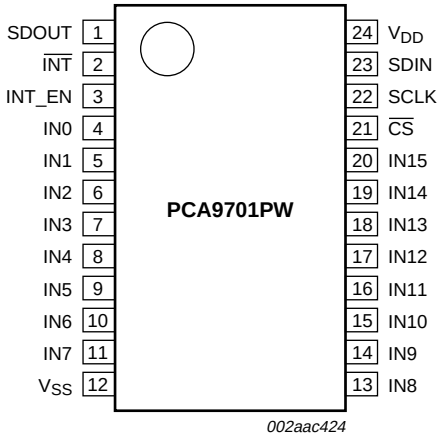


Fig 3. Pin configuration for TSSOP24

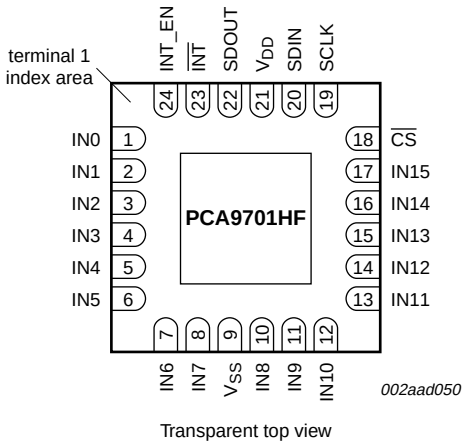


Fig 4. Pin configuration for HWQFN24

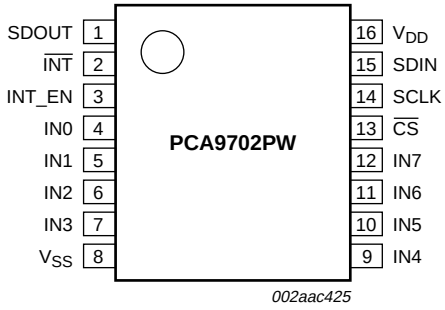


Fig 5. Pin configuration for TSSOP16

6.2 Pin description

Table 2. Pin description

Symbol	Pin			Type	Description
	SO24, TSSOP24	HWQFN24	TSSOP16		
SDOUT	1	22	1	output	3-state serial data output; normally high-impedance
$\overline{INT}$	2	23	2	output	open-drain interrupt output (active LOW)
INT_EN	3	24	3	input	interrupt output enable 1 = interrupt is enabled 0 = interrupt is disabled and high-impedance
IN0	4	1	4	input	input port 0
IN1	5	2	5	input	input port 1
IN2	6	3	6	input	input port 2
IN3	7	4	7	input	input port 3
IN4	8	5	9	input	input port 4
IN5	9	6	10	input	input port 5
IN6	10	7	11	input	input port 6
IN7	11	8	12	input	input port 7
V_{SS}	12	9[1]	8	ground	ground supply
IN8	13	10	-	input	input port 8
IN9	14	11	-	input	input port 9
IN10	15	12	-	input	input port 10
IN11	16	13	-	input	input port 11
IN12	17	14	-	input	input port 12
IN13	18	15	-	input	input port 13
IN14	19	16	-	input	input port 14
IN15	20	17	-	input	input port 15
$\overline{CS}$	21	18	13	input	chip select (active LOW)
SCLK	22	19	14	input	serial input clock
SDIN	23	20	15	input	serial data input (20 μA pull-down)
V_{DD}	24	21	16	supply	supply voltage

[1] HWQFN package die supply ground is connected to both V_{SS} pin and exposed center pad. V_{SS} pin must be connected to supply ground for proper device operation. For enhanced thermal, electrical, and board level performance, the exposed pad needs to be soldered to the board using a corresponding thermal pad on the board and for proper heat conduction through the board, thermal vias need to be incorporated in the PCB in the thermal pad region.

7. Functional description

PCA9701 is a 16-bit General Purpose Input (GPI) with an open-drain interrupt output designed to monitor switch status. By putting an external 100 kΩ series resistor at the input port, the device allows the input to tolerate momentary double 12 V battery, reverse battery, or load dump conditions. The interrupt output is asserted when an input port status changes. The open-drain interrupt output is enabled when INT_EN is HIGH and disabled when INT_EN is LOW. The input port status is accessed via the 4-wire SPI interface. The PCA9702 is the 8-bit version of the PCA9701.

Multiple PCA9701 or PCA9702 devices can be serially connected for monitoring a large number of switches by connecting the SDOUT of one device to the SDIN of the next device. SCLK and $\overline{CS}$ must be common among all devices and interrupt outputs may be tied together. No external logic is necessary because all the devices' interrupt outputs are open-drain that function as 'wired-AND' and can simply be connected together to a single pull-up resistor.

7.1 SPI bus operation

The PCA9701 or PCA9702 interfaces with the controller via the 4-wire SPI bus that is comprised of the following signals: chip select ($\overline{CS}$), serial clock (SCLK), serial data in (SDIN), and serial data out (SDOUT). To access the device, the controller asserts $\overline{CS}$ LOW, then sends SCLK and SDIN. When reading/writing is complete, the controller de-asserts $\overline{CS}$. See Figure 6 for register access timing.

7.1.1 $\overline{CS}$ - chip select

The $\overline{CS}$ pin is the device chip select and is an active LOW input. The falling edge of $\overline{CS}$ captures the input port status in the input status register. If the interrupt output is asserted, the falling edge of $\overline{CS}$ will clear the interrupt. When $\overline{CS}$ is LOW, the SPI interface is active. When $\overline{CS}$ is HIGH, the SPI interface is disabled.

7.1.2 SCLK - serial clock input

SCLK is the serial clock input to the device. It should be LOW and remain LOW during the falling and rising edge of $\overline{CS}$. When $\overline{CS}$ is LOW, the first rising edge of SCLK parallel loads the shift register from the input. The subsequent rising edges on SCLK serially shifts data out from the shift register. The falling edge of SCLK samples the data on SDIN.

7.1.3 SDIN - serial data input

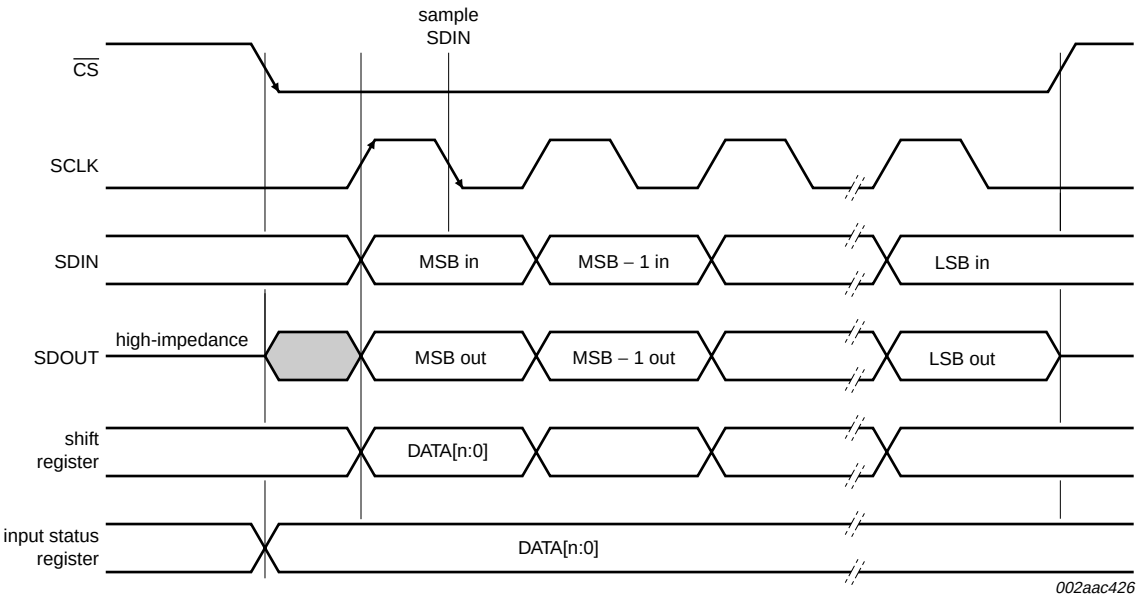
SDIN is the serial data input port. The data is sampled into the shift register on the falling edge of SCLK. SDIN is only active when $\overline{CS}$ is LOW. This input has a 20 µA pull-down current source.

7.1.4 SDOUT - serial data output

SDOUT is the serial data output signal. SDOUT is high-impedance when $\overline{CS}$ is HIGH and switches to low-impedance after $\overline{CS}$ goes LOW. When $\overline{CS}$ is LOW, after the first rising edge of SCLK the most significant bit in the shift register is presented on SDOUT. Subsequent rising edges of SCLK shift the remaining data from the shift register onto SDOUT.

7.1.5 Register access timing

Figure 6 shows the waveforms of the device operation. Initially $\overline{CS}$ is HIGH and SCLK is LOW. On the falling edge of $\overline{CS}$, input port status, DATA[n:0] is captured into the input status register, and subsequently the first rising edge of SCLK parallel loads the shift register. The falling edge of SCLK samples the data on the SDIN. The MSB from the shift register is valid and available on the SDOUT after the first rising edge of SCLK.



DATA[n:0] is data on the input pins, IN[n:0].

For 8-bit GPI (PCA9702), n = 7; for 16-bit GPI (PCA9701), n = 15.

Shaded areas indicate active but invalid data.

Fig 6. Register access timing

7.2 Interrupt output

$\overline{INT}$ is the open-drain interrupt output and is active LOW. A pull-up resistor of approximately 10 kΩ is recommended. The interrupt output is asserted when the input status is changed, and is cleared on the falling edge of $\overline{CS}$ or when the input port status matches the input status register. When there are multiple devices, the $\overline{INT}$ outputs may be tied together to a single pull-up.

Table 3 illustrates the state of the interrupt output versus the state of the input port and input status register. The interrupt output is asserted when the input port and input status register differ.

Table 3. Interrupt output function

H = HIGH; L = LOW; X = don't care

INT_EN	Input port status	Input status register[1]	$\overline{INT}$
H	L	L	high-Z
H	L	H	L
H	H	L	L
H	H	H	high-Z
L	X	X	high-Z

[1] Input status register is the value or content of the D flip-flops.

7.3 General Purpose Inputs

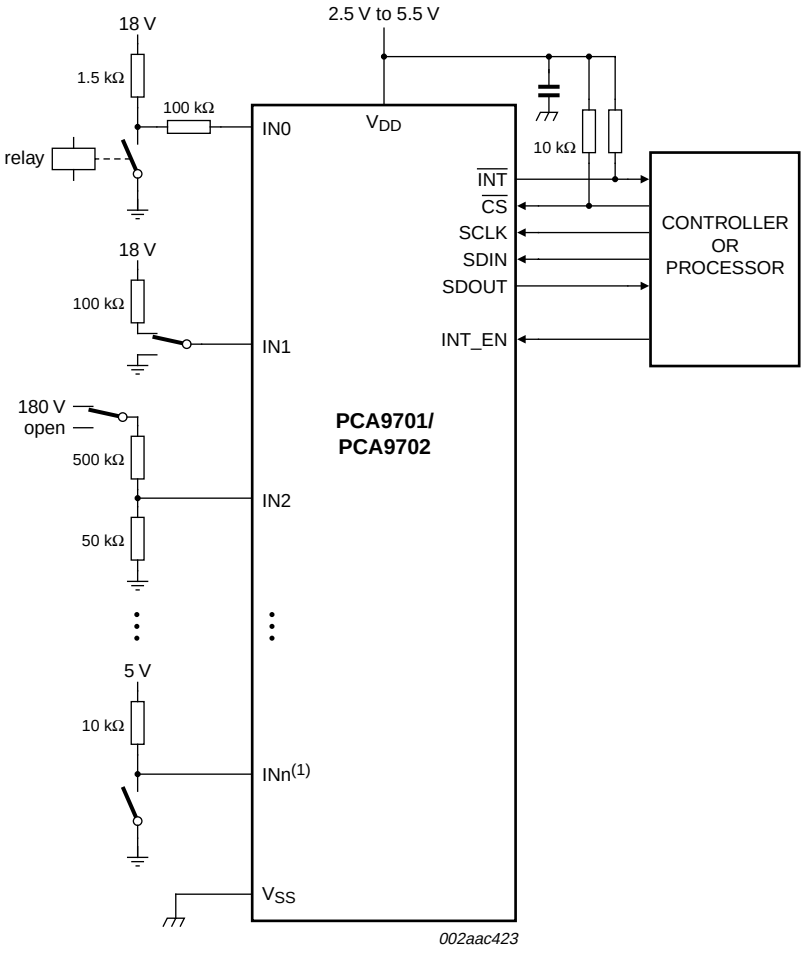
The General Purpose Inputs (GPI) are designed to behave like a typical input in the 0 V to 5.5 V range, but are also designed to have low leakage currents at elevated voltages. The input structure allows for elevated voltages to be applied through a series resistor. The series resistor is required when the input voltage is above 5.5 V. The series resistor is required for two reasons: first, to prevent damage to the input avalanche diode, and second, to prevent the ESD protection circuitry from creating an excessive current flow. The ESD protection circuitry includes a latch-back style device, which provides excellent ESD protection during assembly or typical 5.5 V applications. The series resistor limits the current flowing into the part and provides additional ESD protection. The limited current prevents the ESD latch-back device from latching back to a low voltage, which would cause excessive current flow and damage the part.

The minimum required series resistance for applications with input voltages above 5.5 V is 100 kΩ. For applications requiring an applied voltage above 27 V, Equation 1 is recommended to determine the series resistor. Failure to include the appropriate input series resistor may result in product failure and will void the warranty.

$$R_s = \frac{voltage\ applied - 17\ V}{I_I} \quad (1)$$

The series resistor should be place physically as close as possible to the connected input to reduce the effective node capacitance. The input response time is effected by the RC time constant of the series resistor and the input node capacitance.

8. Application design-in information



(1) n = 15 for PCA9701; n = 7 for PCA9702

Fig 7. Typical application

9. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).
T_{amb} = −40 °C to +125 °C, unless otherwise specified.

Symbol	Parameter	Conditions		Min	Max	Unit
V_{DD}	supply voltage			−0.5	+6.0	V
I_I	input current	IN[n:0] pins with series resistor and V_I > 5.5 V,	[1][2]	-	350	µA
V_I	input voltage	GPI pins IN[n:0]; no series resistor	[1][2]	−0.5	+6	V
		SPI pins		−0.5	+6	V
T_{stg}	storage temperature			−65	+150	°C
$T_{j(max)}$	maximum junction temperature	operating		-	125	°C

[1] With GPI external series resistors, the inputs support double battery, reverse battery and load dump conditions. During double battery or load dump the input pin will drain slightly higher leakage current until the input drops to 18 V. For more detail of leakage current specification, please refer to Table 5 “Static characteristics”. See Section 7.3 for series resistor requirements.

[2] n = 15 for PCA9701; n = 7 for PCA9702.

10. Static characteristics

Table 5. Static characteristics

V_{DD} = 2.5 V to 5.5 V; V_{SS} = 0 V; T_{amb} = −40 °C to +125 °C; unless otherwise specified.

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Supply							
V_{DD}	supply voltage			2.5	3.3	5.5	V
I_{DD}	supply current	V_{DD} = 5.5 V; input = 5 V or 18 V; INT_EN = V_{DD}		-	1.0	2.5	µA
V_{POR}	power-on reset voltage		[1]	-	1.8	2.2	V
General Purpose Inputs							
V_{IL}	LOW-level input voltage			-	-	0.3V_{DD}	V
V_{IH}	HIGH-level input voltage			0.7V_{DD}	-	-	V
I_I	input current	GPI recommended maximum current; V_I > 5.5 V; with series resistor R_S	[2]	-	-	100	µA
I_{IH}	HIGH-level input current	each input; V_I = V_{DD}		−1	-	+1	µA
I_{LI}	input leakage current	V_I = 17 V; 100 kΩ series resistor		−1	-	+1	µA
C_i	input capacitance	V_I = V_{SS} or V_{DD}		-	1.0	2.5	pF
Interrupt output							
I_{OL}	LOW-level output current	V_{DD} = 4.5 V; V_{OL} = 0.4 V		6	-	-	mA
		V_{DD} = 2.5 V; V_{OL} = 0.4 V		3	-	-	mA
I_{OH}	HIGH-level output current	V_{OH} = V_{DD}		−1	-	+1	µA
C_o	output capacitance			-	2	4	pF
SPI and control							
V_{IL}	LOW-level input voltage			-	-	0.3V_{DD}	V
V_{IH}	HIGH-level input voltage			0.7V_{DD}	-	5.5	V
I_{IH}	HIGH-level input current	SDIN; V_I = V_{DD} = 5.5 V		-	20	40	µA
I_{OL}	LOW-level output current	SDOUT; V_{OL} = 0.4 V					
		V_{DD} = 4.5 V		5	-	-	mA
		V_{DD} = 2.5 V		3	-	-	mA
I_{OH}	HIGH-level output current	SDOUT; V_{OH} = V_{DD} − 0.5 V					
		V_{DD} = 4.5 V		5	-	-	mA
		V_{DD} = 2.5 V		3	-	-	mA
C_i	input capacitance	V_I = V_{SS} or V_{DD}		-	2	4	pF
C_o	output capacitance	SDOUT; $\overline{CS}$ = V_{DD}		-	4	6	pF

[1] V_{DD} must be lowered to 0.2 V in order to reset device.

[2] For GPI pin voltages > 5.5 V, see Section 7.3.

11. Dynamic characteristics

Table 6. Dynamic characteristics

V_{DD} = 2.5 V to 5.5 V; V_{SS} = 0 V; T_{amb} = −40 °C to +125 °C; unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
f_{max}	maximum input clock frequency		-	-	5	MHz
t_r	rise time	SDOUT; 10 % to 90 % at 5 V	-	35	60	ns
t_f	fall time	SDOUT; 90 % to 10 % at 5 V	-	25	50	ns
t_{WH}	pulse width HIGH	SCLK	50	-	-	ns
t_{WL}	pulse width LOW	SCLK	50	-	-	ns
$t_{SPILEAD}$	SPI enable lead time	$\overline{CS}$ falling edge to SCLK rising edge	50	-	-	ns
t_{SPILAG}	SPI enable lag time	SCLK falling edge to $\overline{CS}$ rising edge	50	-	-	ns
$t_{su(SDIN)}$	SDIN set-up time	SDIN to SCLK falling edge	20	-	-	ns
$t_{h(SDIN)}$	SDIN hold time	from SCLK falling edge	30	-	-	ns
$t_{en(SDOUT)}$	SDOUT enable time	from $\overline{CS}$ LOW to SDOUT low-impedance; Figure 11	-	-	55	ns
$t_{dis(SDOUT)}$	SDOUT disable time	from rising edge of $\overline{CS}$ to SDOUT high-impedance; Figure 11	-	-	85	ns
$t_{v(SDOUT)}$	SDOUT valid time	from rising edge of SCLK; Figure 12	-	-	55	ns
$t_{su(SCLK)}$	SCLK set-up time	SCLK falling to $\overline{CS}$ falling	50	-	-	ns
$t_{h(SCLK)}$	SCLK hold time	SCLK rising after $\overline{CS}$ rising	50	-	-	ns
t_{POR}	power-on reset pulse time	time before $\overline{CS}$ is active after $V_{DD} > V_{POR}$	-	-	250	ns
$t_{rel(int)}$	interrupt release time	after $\overline{CS}$ going LOW; Figure 13	-	-	500	ns
$t_{v(INT\_N)}$	valid time on pin $\overline{INT}$	after INn changes or INT_EN goes HIGH	-	-	100	ns

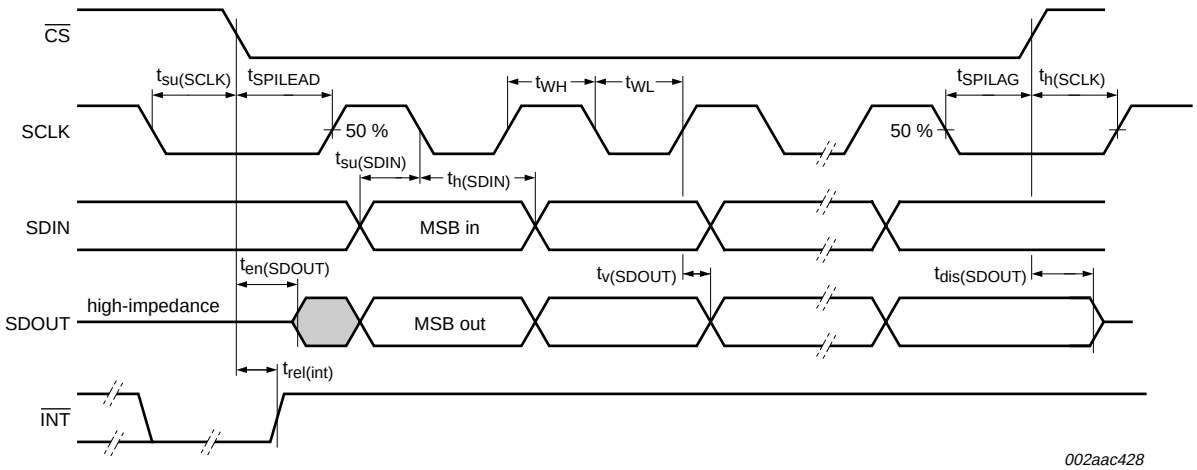


Fig 8. Timing diagram

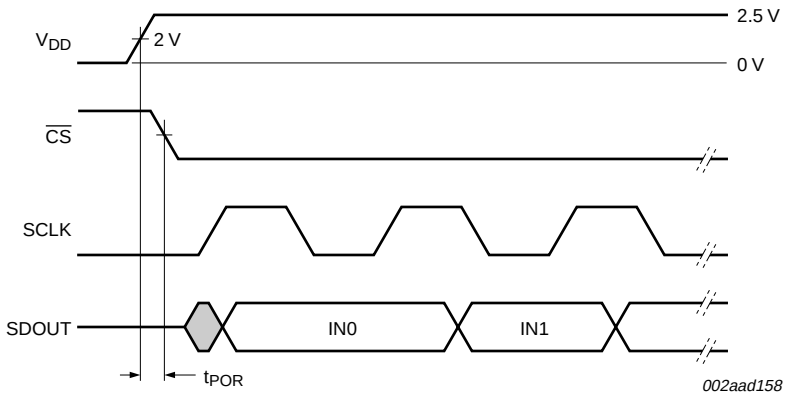


Fig 9. AC waveform for t_{POR} timing

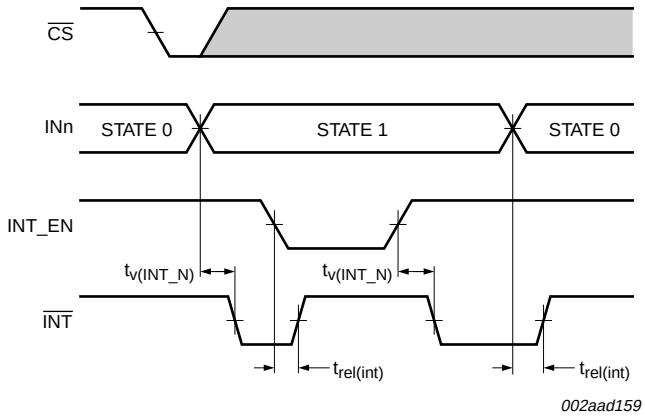


Fig 10. AC waveform for $\overline{INT}$ timing

12. Test information

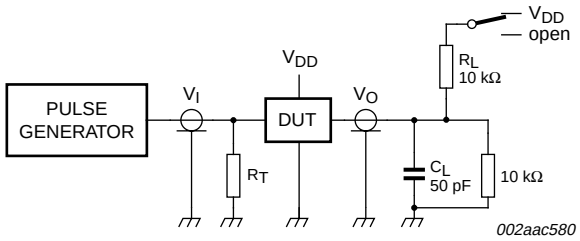


Fig 11. Test circuitry for enable/disable times, SDOUT ($t_{en(SDOUT)}$ and $t_{dis(SDOUT)}$)

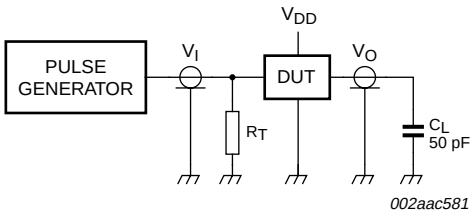


Fig 12. Test circuitry for switching times, SDOUT ($t_{v(SDOUT)}$)

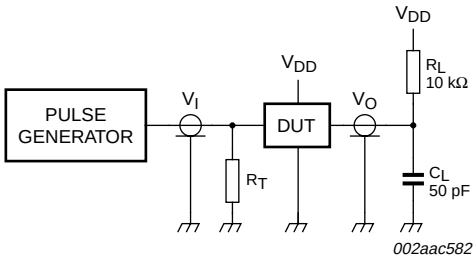


Fig 13. Test circuitry for switching times, $\overline{INT}$

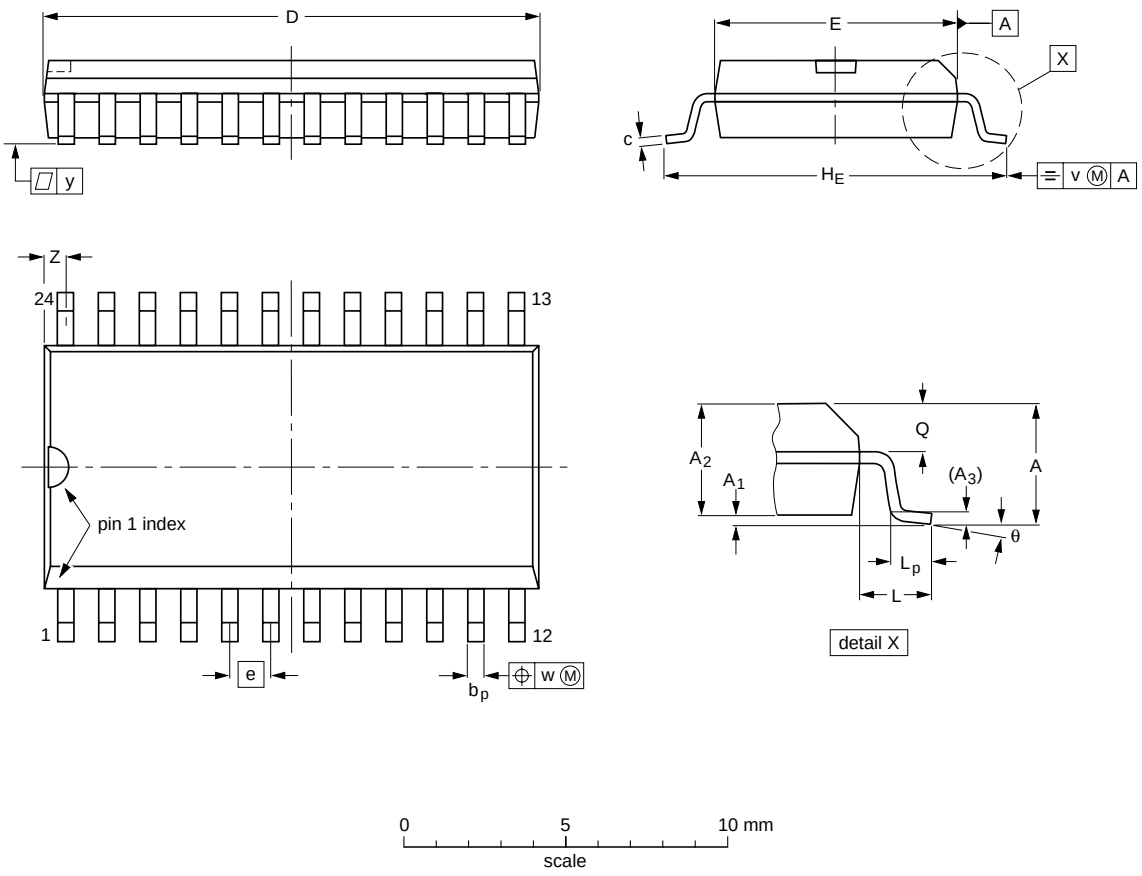
R_L = load resistance.

C_L = load capacitance includes jig and probe capacitance.

R_T = termination resistance should be equal to the output impedance Z_o of the pulse generators.

13. Package outline

SO24: plastic small outline package; 24 leads; body width 7.5 mm **SOT137-1**



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	D (1)	E (1)	e	H_E	L	L_p	Q	v	w	y	Z (1)	θ
mm	2.65	0.3 0.1	2.45 2.25	0.25	0.49 0.36	0.32 0.23	15.6 15.2	7.6 7.4	1.27	10.65 10.00	1.4	1.1 0.4	1.1 1.0	0.25	0.25	0.1	0.9 0.4	8^o 0^o
inches	0.1	0.012 0.004	0.096 0.089	0.01	0.019 0.014	0.013 0.009	0.61 0.60	0.30 0.29	0.05	0.419 0.394	0.055	0.043 0.016	0.043 0.039	0.01	0.01	0.004	0.035 0.016	

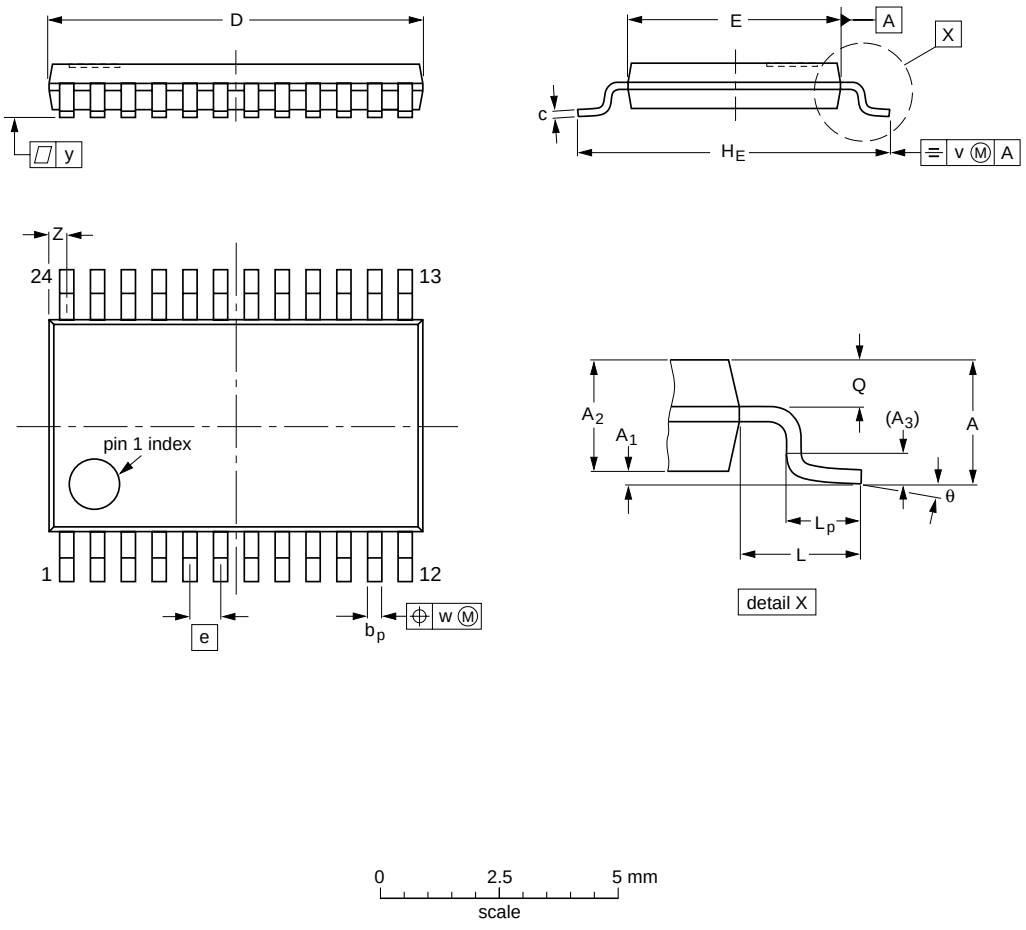
Note

1. Plastic or metal protrusions of 0.15 mm (0.006 inch) maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT137-1	075E05	MS-013				~~99-12-27~~ 03-02-19

Fig 14. Package outline SOT137-1 (SO24)

TSSOP24: plastic thin shrink small outline package; 24 leads; body width 4.4 mm **SOT355-1**



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	$D^{(1)}$	$E^{(2)}$	e	H_E	L	L_p	Q	v	w	y	$Z^{(1)}$	θ
mm	1.1	0.15 0.05	0.95 0.80	0.25	0.30 0.19	0.2 0.1	7.9 7.7	4.5 4.3	0.65	6.6 6.2	1	0.75 0.50	0.4 0.3	0.2	0.13	0.1	0.5 0.2	8^o 0^o

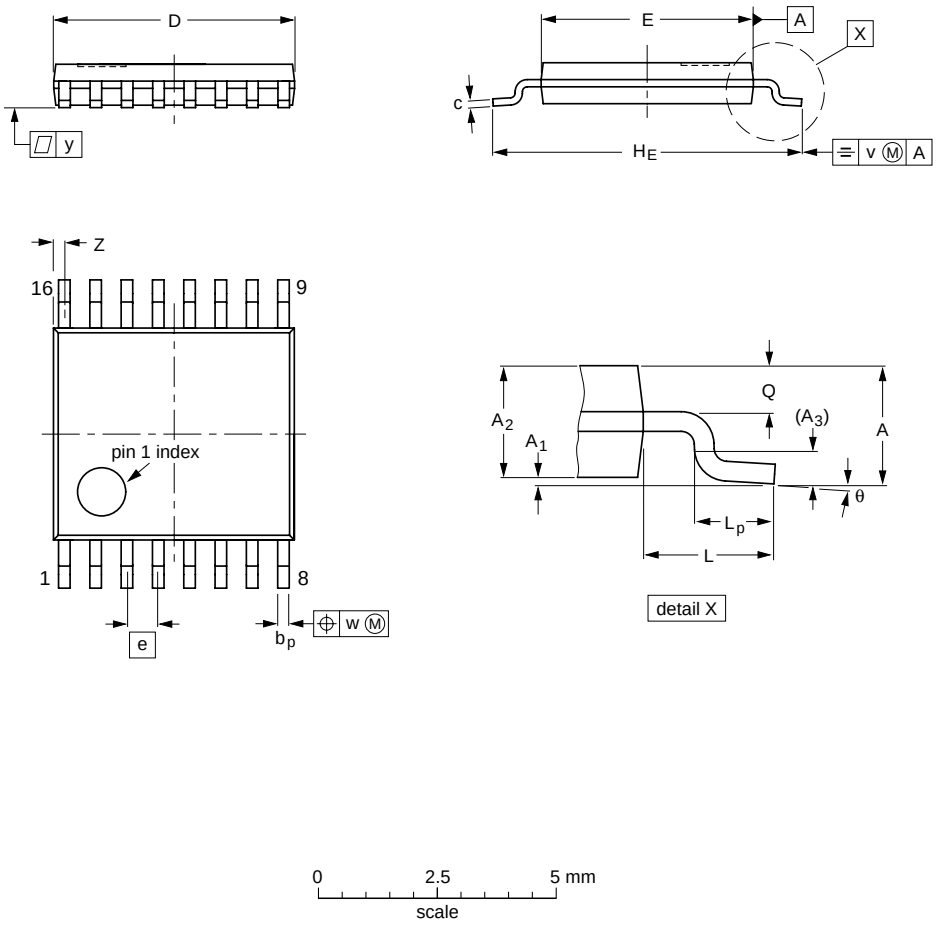
Notes

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT355-1		MO-153				~~99-12-27~~ 03-02-19

Fig 15. Package outline SOT355-1 (TSSOP24)

TSSOP16: plastic thin shrink small outline package; 16 leads; body width 4.4 mm **SOT403-1**



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	D (1)	E (2)	e	H_E	L	L_p	Q	v	w	y	Z (1)	θ
mm	1.1	0.15 0.05	0.95 0.80	0.25	0.30 0.19	0.2 0.1	5.1 4.9	4.5 4.3	0.65	6.6 6.2	1	0.75 0.50	0.4 0.3	0.2	0.13	0.1	0.40 0.06	8^o 0^o

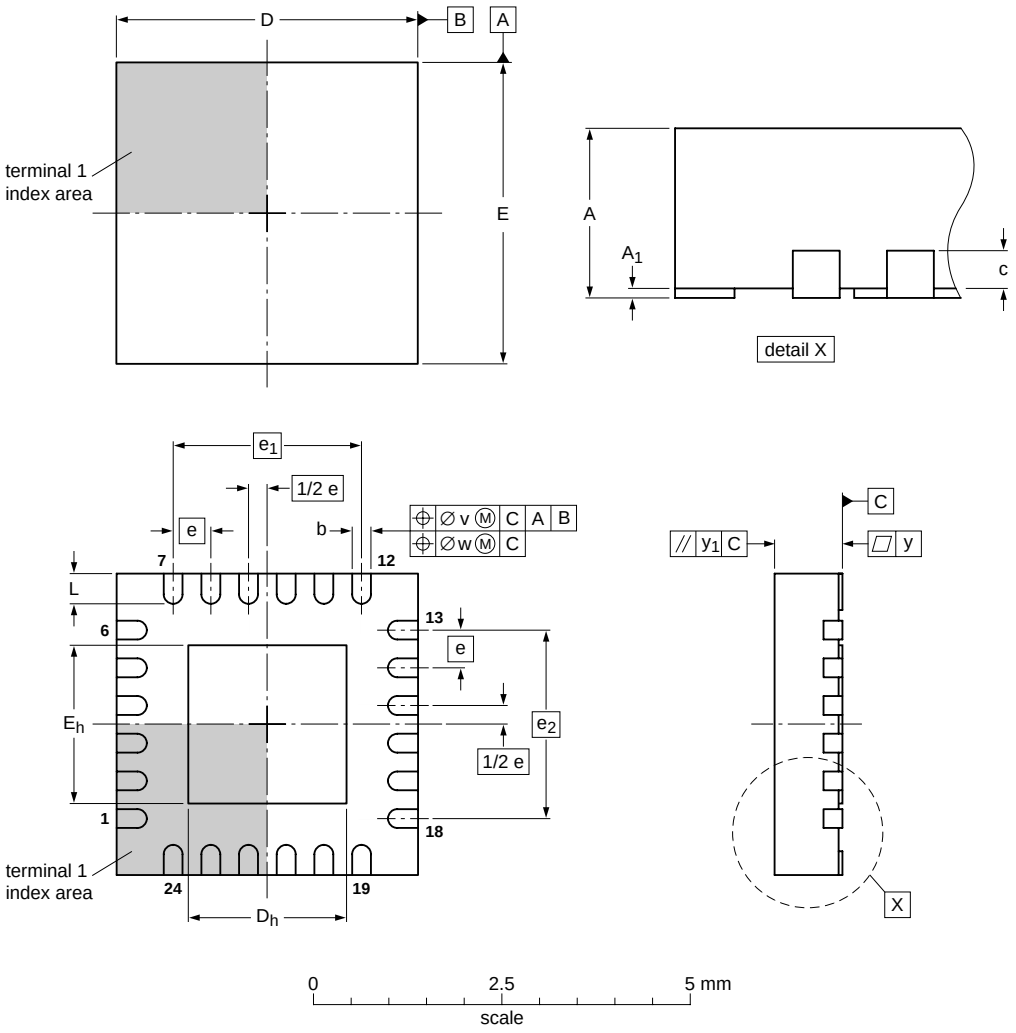
Notes

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT403-1		MO-153				~~99-12-27~~ 03-02-18

Fig 16. Package outline SOT403-1 (TSSOP16)

HWQFN24: plastic thermal enhanced very very thin quad flat package; no leads; 24 terminals; body 4 x 4 x 0.75 mm **SOT994-1**



DIMENSIONS (mm are the original dimensions)

UNIT	A(1) max	A_1	b	c	D(1)	D_h	E(1)	E_h	e	e_1	e_2	L	v	w	y	y_1
mm	0.8	0.05 0.00	0.30 0.18	0.2	4.1 3.9	2.25 1.95	4.1 3.9	2.25 1.95	0.5	2.5	2.5	0.5 0.3	0.1	0.05	0.05	0.1

Note

1. Plastic or metal protrusions of 0.075 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT994-1	- - -	MO-220	- - -			~~07-02-07~~ 07-03-03

Fig 17. Package outline SOT994-1 (HWQFN24)

14. Soldering

This text provides a very brief insight into a complex technology. A more in-depth account of soldering ICs can be found in Application Note *AN10365 "Surface mount reflow soldering description"*.

14.1 Introduction to soldering

Soldering is one of the most common methods through which packages are attached to Printed Circuit Boards (PCBs), to form electrical circuits. The soldered joint provides both the mechanical and the electrical connection. There is no single soldering method that is ideal for all IC packages. Wave soldering is often preferred when through-hole and Surface Mount Devices (SMDs) are mixed on one printed wiring board; however, it is not suitable for fine pitch SMDs. Reflow soldering is ideal for the small pitches and high densities that come with increased miniaturization.

14.2 Wave and reflow soldering

Wave soldering is a joining technology in which the joints are made by solder coming from a standing wave of liquid solder. The wave soldering process is suitable for the following:

- Through-hole components
- Leaded or leadless SMDs, which are glued to the surface of the printed circuit board

Not all SMDs can be wave soldered. Packages with solder balls, and some leadless packages which have solder lands underneath the body, cannot be wave soldered. Also, leaded SMDs with leads having a pitch smaller than ~0.6 mm cannot be wave soldered, due to an increased probability of bridging.

The reflow soldering process involves applying solder paste to a board, followed by component placement and exposure to a temperature profile. Leaded packages, packages with solder balls, and leadless packages are all reflow solderable.

Key characteristics in both wave and reflow soldering are:

- Board specifications, including the board finish, solder masks and vias
- Package footprints, including solder thieves and orientation
- The moisture sensitivity level of the packages
- Package placement
- Inspection and repair
- Lead-free soldering versus PbSn soldering

14.3 Wave soldering

Key characteristics in wave soldering are:

- Process issues, such as application of adhesive and flux, clinching of leads, board transport, the solder wave parameters, and the time during which components are exposed to the wave
- Solder bath specifications, including temperature and impurities

14.4 Reflow soldering

Key characteristics in reflow soldering are:

- Lead-free versus SnPb soldering; note that a lead-free reflow process usually leads to higher minimum peak temperatures (see Figure 18) than a PbSn process, thus reducing the process window
- Solder paste printing issues including smearing, release, and adjusting the process window for a mix of large and small components on one board
- Reflow temperature profile; this profile includes preheat, reflow (in which the board is heated to the peak temperature) and cooling down. It is imperative that the peak temperature is high enough for the solder to make reliable solder joints (a solder paste characteristic). In addition, the peak temperature must be low enough that the packages and/or boards are not damaged. The peak temperature of the package depends on package thickness and volume and is classified in accordance with Table 7 and 8

Table 7. SnPb eutectic process (from J-STD-020C)

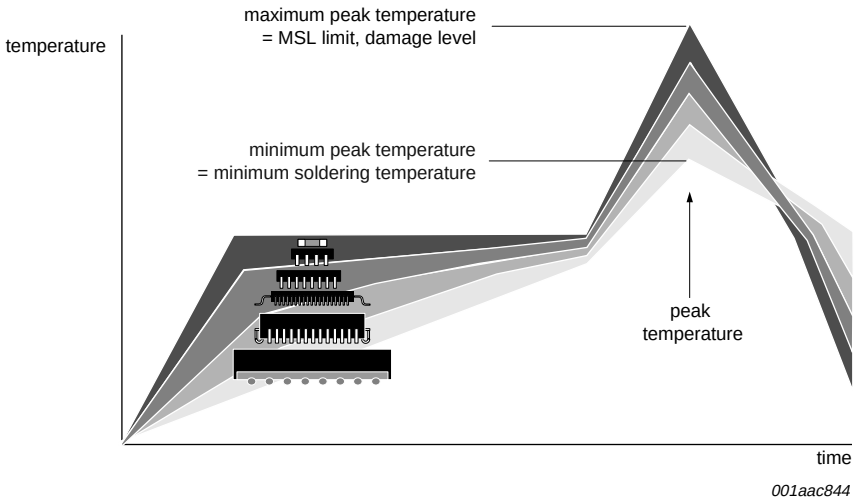
Package thickness (mm)	Package reflow temperature (°C)	
	Volume (mm^3)	
	< 350	≥ 350
< 2.5	235	220
≥ 2.5	220	220

Table 8. Lead-free process (from J-STD-020C)

Package thickness (mm)	Package reflow temperature (°C)		
	Volume (mm^3)		
	< 350	350 to 2000	> 2000
< 1.6	260	260	260
1.6 to 2.5	260	250	245
> 2.5	250	245	245

Moisture sensitivity precautions, as indicated on the packing, must be respected at all times.

Studies have shown that small packages reach higher temperatures during reflow soldering, see Figure 18.



MSL: Moisture Sensitivity Level

Fig 18. Temperature profiles for large and small components

For further information on temperature profiles, refer to Application Note *AN10365 "Surface mount reflow soldering description"*.

15. Abbreviations

Table 9. Abbreviations

Acronym	Description
CDM	Charged Device Model
DUT	Device Under Test
ESD	ElectroStatic Discharge
GPI	General Purpose Input
HBM	Human Body Model
MM	Machine Model
MSB	Most Significant Bit
PCB	Printed-Circuit Board
RC	Resistor-Capacitor network
SPI	Serial Peripheral Interface

16. Revision history

Table 10. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
PCA9701_PCA9702_2	20070829	Product data sheet	-	PCA9701_PCA9702_1

Modifications:

- Section 1 “General description” rewritten
- Section 2 “Features”:
  - first 2 bullet items merged
  - added (new) 6th, 8th and 10th bullet items
  - “4 kV HBM ESD protection” changed to (new) 9th bullet item
  - 12th bullet: changed “HVQFN24” to “HWQFN24”
- Table 1 “Ordering information”:
  - deleted type number PCA9701BS
  - added type number PCA9701HF
  - Topside mark for PCA9702PW changed from “PCA9702PW” to “PCA9702”
- Section 6 “Pinning information”
  - deleted pin configuration HVQFN24
  - added pin configuration HWQFN24
  - Table 2 “Pin description”, Table note 1: changed “HVQFN” to “HWQFN”
- added (new) Section 7.3 “General Purpose Inputs”
- Table 4 “Limiting values”:
  - removed V_n specification
  - added I_I, input current specification
  - specification V_I modified
  - Table note 1 modified
- Table 5 “Static characteristics”:
  - sub-section “Supply”: changed Typ value from “-” to “1.0 µA”; changed Max value from “5 µA” to “2.5 µA”
  - added Table note 1 and its reference at V_{POR}
  - sub-section “General Purpose Inputs”: changed V_{IL} Min from “0” to “-”; changed V_{IL} Max from “$0.4V_{DD}$” to “$0.3V_{DD}$”
  - sub-section “General Purpose Inputs”: changed V_{IH} Max from “5.5 V” to “-”
  - sub-section “General Purpose Inputs”, symbol V_{IH}: removed spec with condition “100 kΩ series resistor”
  - sub-section “General Purpose Inputs”: added specification for I_I, and Table note 2
  - sub-section “General Purpose Inputs”, symbol I_{LI}: Conditions changed from “V_I = 18 V” to “V_I = 17 V”; min value changed from “-” to “–1 µA”; typ value changed from “30 µA” to “+0.1 µA”; max value changed from “-” to “+1 µA”
  - sub-section “General Purpose Inputs”: changed C_i Typ from “-” to “1.0 pF”; changed C_i Max from “5 pF” to “2.5 pF”
  - sub-section “Interrupt output”, I_{OL} condition: added “V_{OL} = 0.4 V”
  - sub-section “Interrupt output”: added specification for I_{OL} with condition “V_{DD} = 2.5 V; V_{OL} = 0.4 V”
  - sub-section “Interrupt output”: added C_o, output capacitance specification

Table 10. Revision history *...continued*

Document ID	Release date	Data sheet status	Change notice	Supersedes
Modifications (continued):	• Table 5 “Static characteristics” (continued): – changed sub-section title “SPI” to “SPI and control” – sub-section “SPI and control”: changed V_{IL} Min from “0” to “-” – sub-section “SPI and control”: changed I_{OL} Min from “6 mA” to “5 mA” – sub-section “SPI and control”: added specification for I_{OL} with condition V_{DD} = 2.5 V – sub-section “SPI and control”, I_{OH} conditions changed from “V_{OH} = 4.0 V” to “$V_{OH} = V_{DD} - 0.5$ V” – sub-section “SPI and control”: changed I_{OH} Min from “6 mA” to “5 mA” – sub-section “SPI and control”: added specification for I_{OH} with condition V_{DD} = 2.5 V – sub-section “SPI and control”: changed C_i Typ from “-” to “2 pF”; changed C_i Max from “5 pF” to “4 pF” – sub-section “SPI and control”: changed C_o Typ from “6 pF” to “4 pF”; changed C_o Max from “-” to “6 pF” • Table 6 “Dynamic characteristics”: – t_r Typ changed from “19 ns” to “35 ns”; t_r Max changed from “-” to “60 ns” – t_f Typ changed from “21 ns” to “25 ns”; t_f Max changed from “-” to “50 ns” – changed $t_{dis(SDOUT)}$ max value from “55 ns” to “85 ns” – t_{POR} conditions: changed “time before part is active” to “time before $\overline{CS}$ is active” – added $t_{v(INT\_N)}$ specification – Figure 8 modified – added Figure 9 and Figure 10 • Section 12 “Test information”: – Figure 11 “Test circuitry for enable/disable times, SDOUT ($t_{en(SDOUT)}$ and $t_{dis(SDOUT)}$)” modified • Section 13 “Package outline”: – deleted package outline SOT905-1 (HVQFN24) – added Figure 17 “Package outline SOT994-1 (HWQFN24)”		
PCA9701_PCA9702_1	20070323	Objective data sheet	-	-

17. Legal information

17.1 Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL http://www.nxp.com.

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